

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>You Wang</td><td>06/23/2006</td></tr><tr><td>Jie Dao</td><td>06/26/2006</td></tr><tr><td>Stan D. Tsai</td><td>06/23/2006</td></tr><tr><td>Lakshmanan Karuppiiah</td><td>07/12/2006</td></tr></tbody></table>	Name	Execution Date	You Wang	06/23/2006	Jie Dao	06/26/2006	Stan D. Tsai	06/23/2006	Lakshmanan Karuppiiah	07/12/2006	
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RECEIVING PARTY DATA											
Name:	Applied Materials, Inc.										
Street Address:	P. O. Box 450A										
City:	Santa Clara										
State/Country:	CALIFORNIA										
Postal Code:	95052										
PROPERTY NUMBERS Total: 1											
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>11483843</td></tr></tbody></table>	Property Type	Number	Application Number:	11483843							
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Application Number:	11483843										
CORRESPONDENCE DATA											
Fax Number:	(408)986-3090										
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
Email:	barbara_holt@amat.com										
Correspondent Name:	Applied Materials										
Address Line 1:	P.O. Box 450A										
Address Line 4:	Santa Clara, CALIFORNIA 95052										
ATTORNEY DOCKET NUMBER:	10724/PPC/CMP										
NAME OF SUBMITTER:	Barbara Holt										
Total Attachments: 2 source=10724 _asg 081106#page1.tif source=10724 _asg 081106#page2.tif											

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PATENT

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REEL: 018112 FRAME: 0929

ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Names and Addresses of Inventors:

1)	You Wang 22653 Queens Oak Court Cupertino, CA 95014	2)	Jie Diao 4290 Albany Drive #P245 San Jose, California 95129
3)	Stan D. Tsai 5444 Dekker Terrace Fremont, CA 94555	4)	Lakshmanan Karuppiyah 2720 Sycamore Grove Place San Jose, CA 95121

(hereinafter referred to as Assignors), have invented a certain invention entitled:

**A METHOD AND APPARATUS FOR ELECTROPROCESSING A SUBSTRATE WITH
EDGE PROFILE CONTROL**

enclosed herewith or for which application for Letters Patent in the United States was filed on _____, under Serial No. _____, executed on even date herewith; and

WHEREAS, Applied Materials, Inc., a corporation of the State of Delaware, having a place of business at 3050 Bowers Avenue, Santa Clara, California 95054 (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said application (hereinafter referred to as Application), and the invention disclosed therein (hereinafter referred to as Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignors, and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter referred to as Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

1. Said Assignors hereby sell, assign, transfer and convey to Assignee the full and exclusive right, title and interest (a) in and to said Application and said Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a conventional, division, substitution, or continuation of said Application; and (d) in and to each and every reissue or extension of any of said

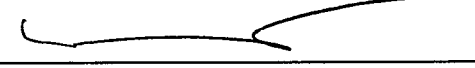

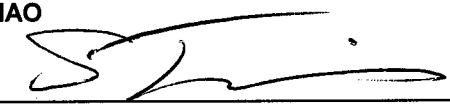
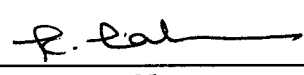
Patents.

2. Said Assignors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting conventional, substitute, divisional, continuing or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefor and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Assignors, their respective heirs, legal representatives and assigns.

4. Said Assignors hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

1)	<u>6-23-2006</u> (DATE)	 _____ YOU WANG
2)	<u>06-26-2006</u> (DATE)	 _____ JIE DIAO
3)	<u>6/23/06</u> (DATE)	 _____ STAN D. TSAI
4)	<u>7/12/06</u> (DATE)	 _____ LAKSHMANAN KARUPPIAH